

<b>Notice of References Cited</b>		Application/Control No.	Applicant(s)/Patent Under Reexamination	
		09/943,196	MAY, CHARLES E.	
Examiner		Art Unit		Page 1 of 1
Lynette T. Umez-Eronini		1765		

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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.